

2SK2425

Silicon N Channel MOS FET

REJ03G1012-0200

(Previous: ADE-208-1360)

Rev.2.00 Sep 07, 2005

Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator, DC-DC converter.

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	250	V
Gate to source voltage	V _{GSS}	±30	V
Drain current	I _D	7	А
Drain peak current	I _{D(pulse)} *1	28	А
Body to drain diode reverse drain current	I _{DR}	7	А
Channel dissipation	Pch*2	30	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

2. Value at Tc = 25°C

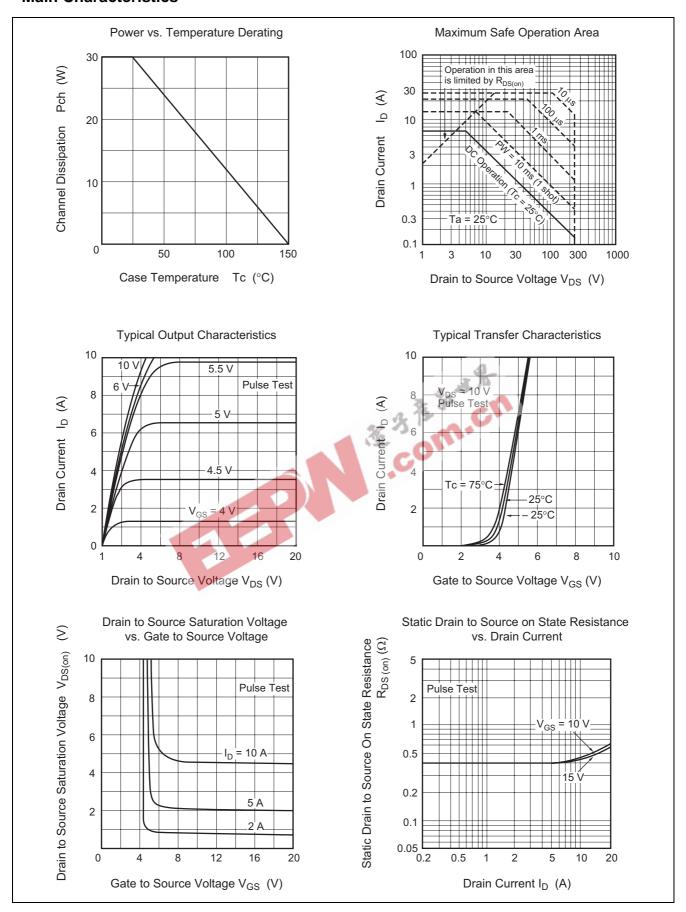
Electrical Characteristics

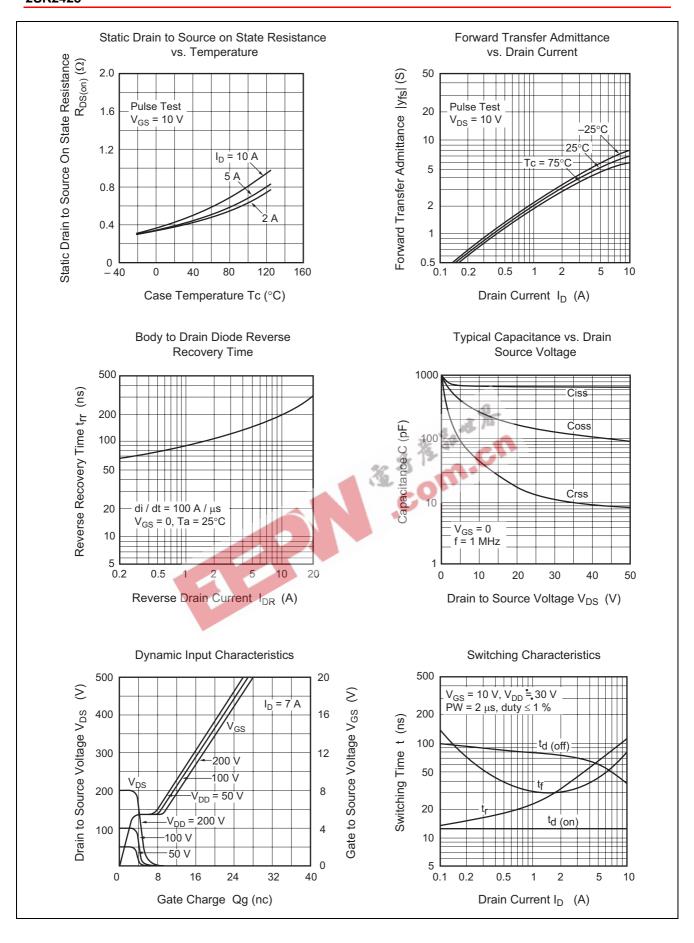
 $(Ta = 25^{\circ}C)$

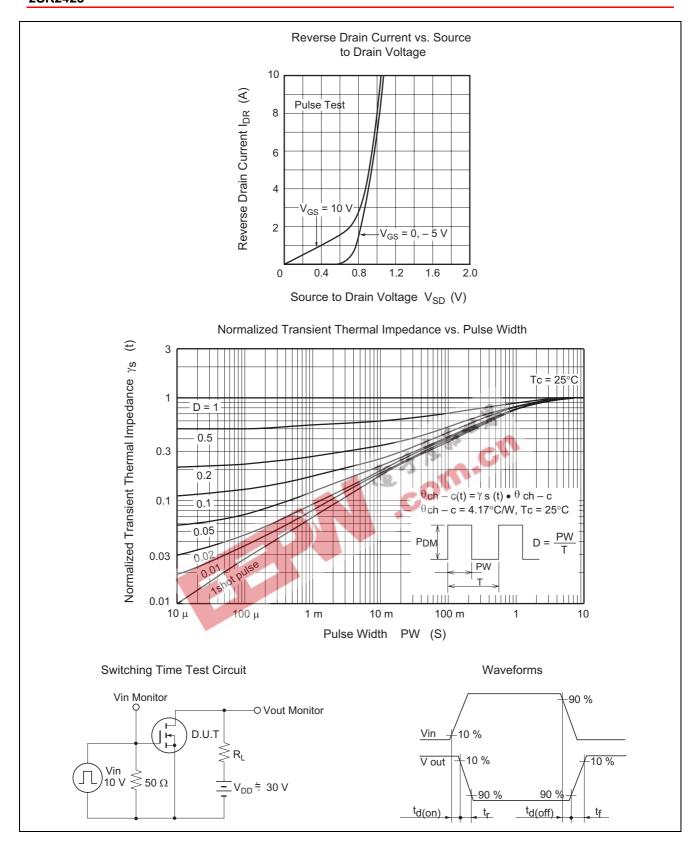
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	250		_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±30		_	V	$I_G = \pm 100 \; \mu A, \; V_{DS} = 0$
Gate to source leak current	I_{GSS}	_		±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_		250	μΑ	$V_{DS} = 250 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	2.0	_	3.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state	R _{DS(on)}	_	0.4	0.55	Ω	$I_D = 4 \text{ A}, V_{GS} = 10 \text{ V}^{*3}$
resistance			26	S) (
Forward transfer admittance	y _{fs}	3.0	5.0	~O)	S	$I_D = 4 \text{ A}, V_{DS} = 10 \text{ V}^{*3}$
Input capacitance	Ciss	4	6 90		pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss		265	_	рF	f = 1 MHz
Reverse transfer capacitance	Crss	+	45		рF	
Turn-on delay time	t _{d(on)}		13	_	ns	$I_D = 4 A, V_{GS} = 10 V,$
Rise time	t _r	_	55	_	ns	$R_L = 7.5 \Omega$
Turn-off delay time	t _{d(off)}	_	65	_	ns	
Fall time	t _f	_	37	_	ns	
Body to drain diode forward voltage	V _{DF}	_	1.0	_	V	$I_F = 7 A, V_{GS} = 0$
Body to drain diode reverse	t _{rr}	_	180	_	ns	$I_F = 7 A$, $V_{GS} = 0$,
recovery time						di _F / dt = 100 A / μs

Note: 3. Pulse Test

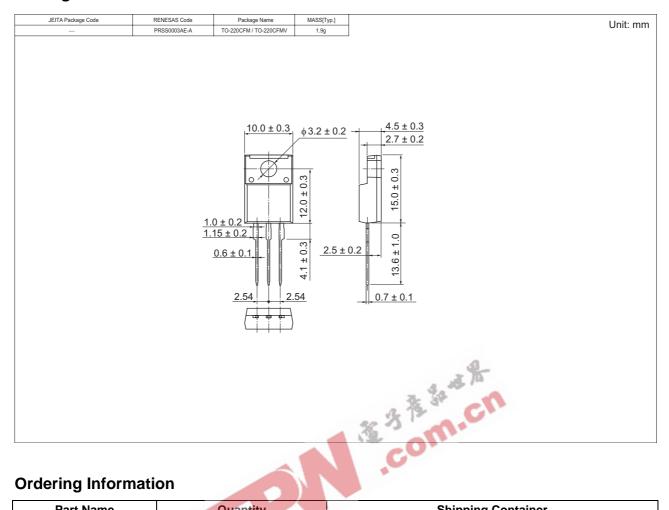
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity		Shipping Container
2SK2425-E	600 pcs	Box (Tube)	

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